

Features

- New Thin Wafer Technology
- Low Forward Voltage Drop (V_F)
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- Positive Temperature Coefficient on V_F
- Temperature-independent Switching

V_{RRM}	=	650	V
$I_F (T_C \leq 147^\circ C)$	=	30	A
Q_C	=	68	nC

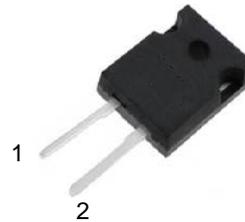
Benefits

- Replace Bipolar with Unipolar Device
- Reduction of Heat Sink Size
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

Applications

- Switch Mode Power Supplies
- Uninterruptible Power Supplies
- Motor drive, PV Inverter, Wind Power Station

Package



TO-247-2



Part Number	Package	Marking
AS4D030065C	TO-247-2	AS4D030065C

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{RRM}	Repetitive Peak Reverse Voltage	650	V	$T_C = 25^\circ\text{C}$	
V_{RSM}	Surge Peak Reverse Voltage	650	V	$T_C = 25^\circ\text{C}$	
V_R	DC Blocking Voltage	650	V	$T_C = 25^\circ\text{C}$	
I_F	Forward Current	38 30	A	$T_C \leq 135^\circ\text{C}$ $T_C \leq 147^\circ\text{C}$	
I_{FSM}	Non-Repetitive Forward Surge Current	220	A	$T_C = 25^\circ\text{C}$, $t_p = 8.3\text{ms}$, Half Sine Wave	
P_{tot}	Power Dissipation	234	W	$T_C = 25^\circ\text{C}$	Fig.3
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to 175	$^\circ\text{C}$		
T_{sold}	Soldering Temperature	260	$^\circ\text{C}$		

Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_F	Forward Voltage	1.3 1.4	1.5 1.7	V	$I_F = 30\text{A}$, $T_J = 25^\circ\text{C}$ $I_F = 30\text{A}$, $T_J = 175^\circ\text{C}$	Fig.1
I_R	Reverse Current	20 80	200 1000	μA	$V_R = 650\text{V}$, $T_J = 25^\circ\text{C}$ $V_R = 650\text{V}$, $T_J = 175^\circ\text{C}$	Fig.2
C	Total Capacitance	1820 187 136	/	pF	$V_R = 0.1\text{V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{MHz}$ $V_R = 200\text{V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{MHz}$ $V_R = 400\text{V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{MHz}$	Fig.5
Q_C	Total Capacitive Charge	68	/	nC	$V_R = 400\text{V}$, $I_F = 30\text{A}$ $di/dt = 200\text{A}/\mu\text{s}$, $T_J = 25^\circ\text{C}$	Fig.4

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.64	$^\circ\text{C}/\text{W}$	Fig.6
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	80	$^\circ\text{C}/\text{W}$	

Electrical Characteristic Curves

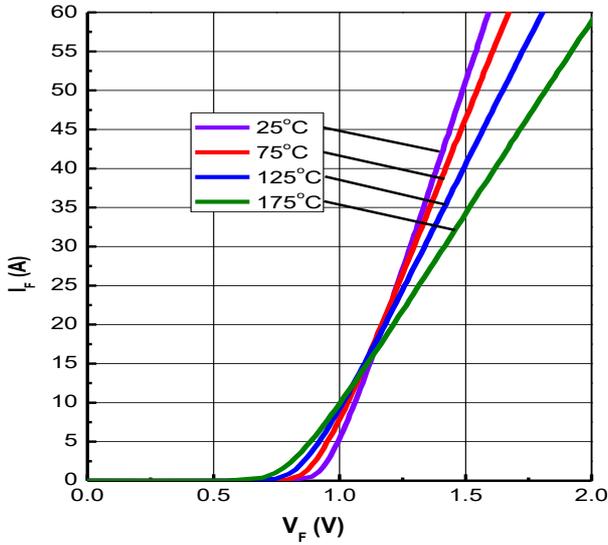


Figure 1. Forward Characteristics

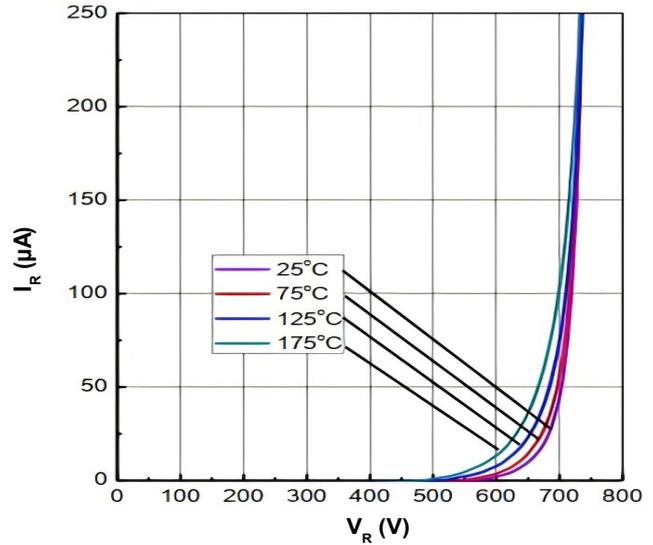


Figure 2. Reverse Characteristics

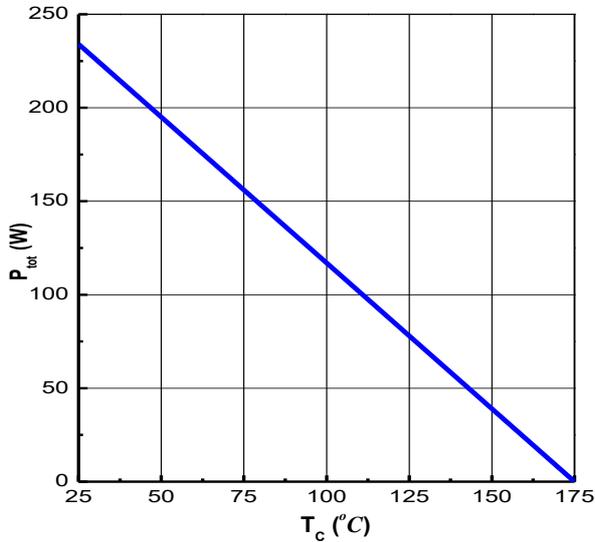


Figure 3. Power Derating

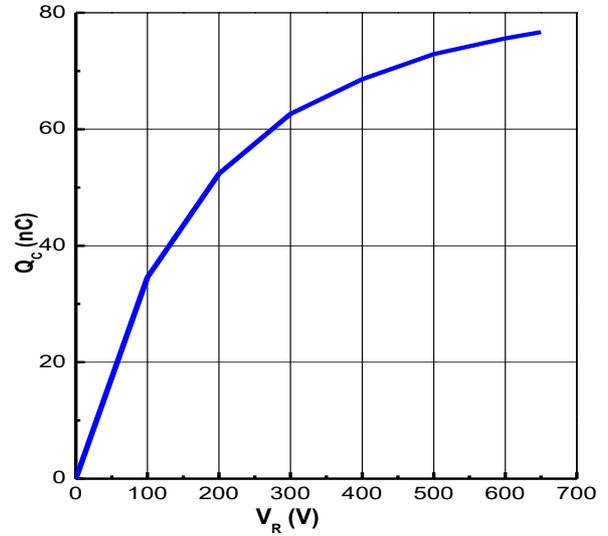


Figure 4. Total Capacitive Charge vs. Reverse Voltage

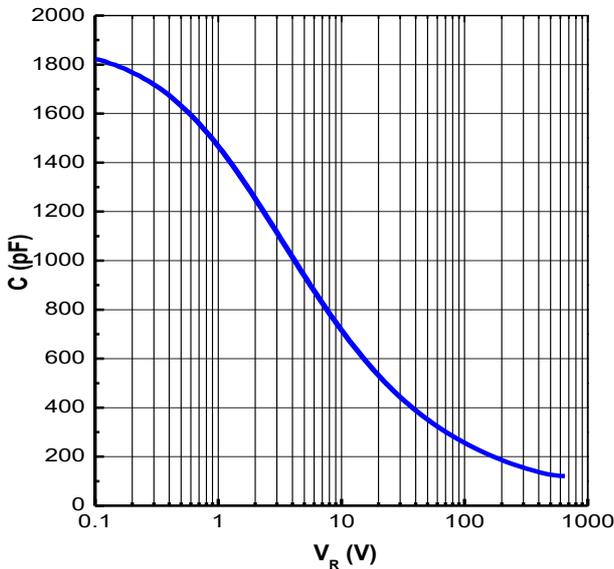


Figure 5. Total Capacitance vs. Reverse Voltage

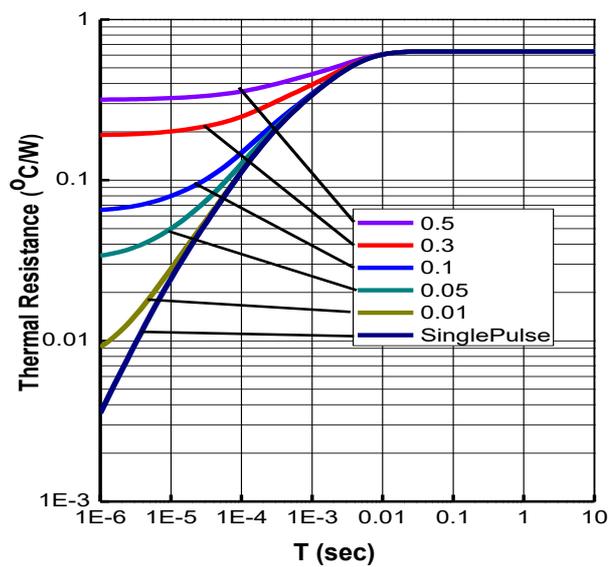
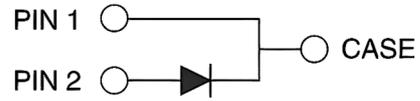
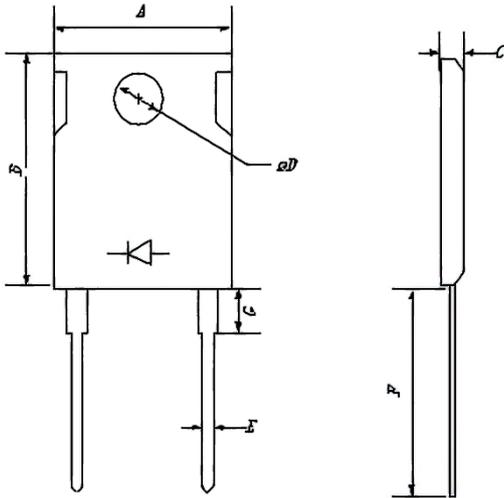


Figure 6. Transient Thermal Impedance

TO-247-2 Package Dimensions



Symbols	Min. (mm)	Typ. (mm)	Max. (mm)
A	14.18	15.75	17.33
B	18.45	20.5	22.55
C	4.50	5.00	5.50
D	3.15	3.50	3.85
E	1.08	1.20	1.32
F	18.27	20.30	22.33
G	3.80	4.10	4.40